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(71) Applicant (for all designated States except US): **ISMECA SEMICONDUCTOR HOLDING SA** [CH/CH]; Rue de l'Helvétie 283, CH-2300 La Chaux-de-Fonds (CH).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **MUNIZ, David** [IT/CH]; Rue Blaise Cendrars 2, CH-2304 La Chaux-de-Fonds (CH). **CHONG, Sek Hoi** [MY/MY]; Jalan TBC 25, Taman Bukit Cheng, Melaka, 75250 (MY).

(74) Agent: **P&TS**; Av. J.-J. Rousseau 4, BP 2848, CH-2001 Neuchâtel (CH).

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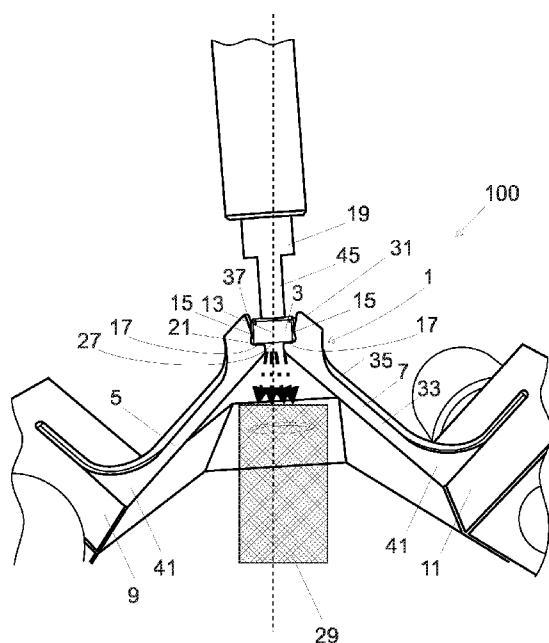


Fig. 1

(57) Abstract: According to the invention, there is provided a clamping test contacting setup, suitable for clamping a component so that the component is held in a fixed position while being processed, the clamp comprising, a first finger which is pivotally mounted at a first pivot point and the second finger which is pivotally mounted at a second pivot point, so that the first finger and a second finger can each pivot towards a central plane; wherein the first finger and a second finger each comprise a surface suitable for cooperating with a component to be clamped, wherein the first finger and a second finger each comprise a stop means which is suitable for cooperating with a component to be clamped to restrict movement of the component with respect to the respective finger, so that applying a force to the component will cause the first and second fingers to clamp the component. There is further provided a processing station which comprises such a clamp and a corresponding method of clamping a component and method of processing a component.